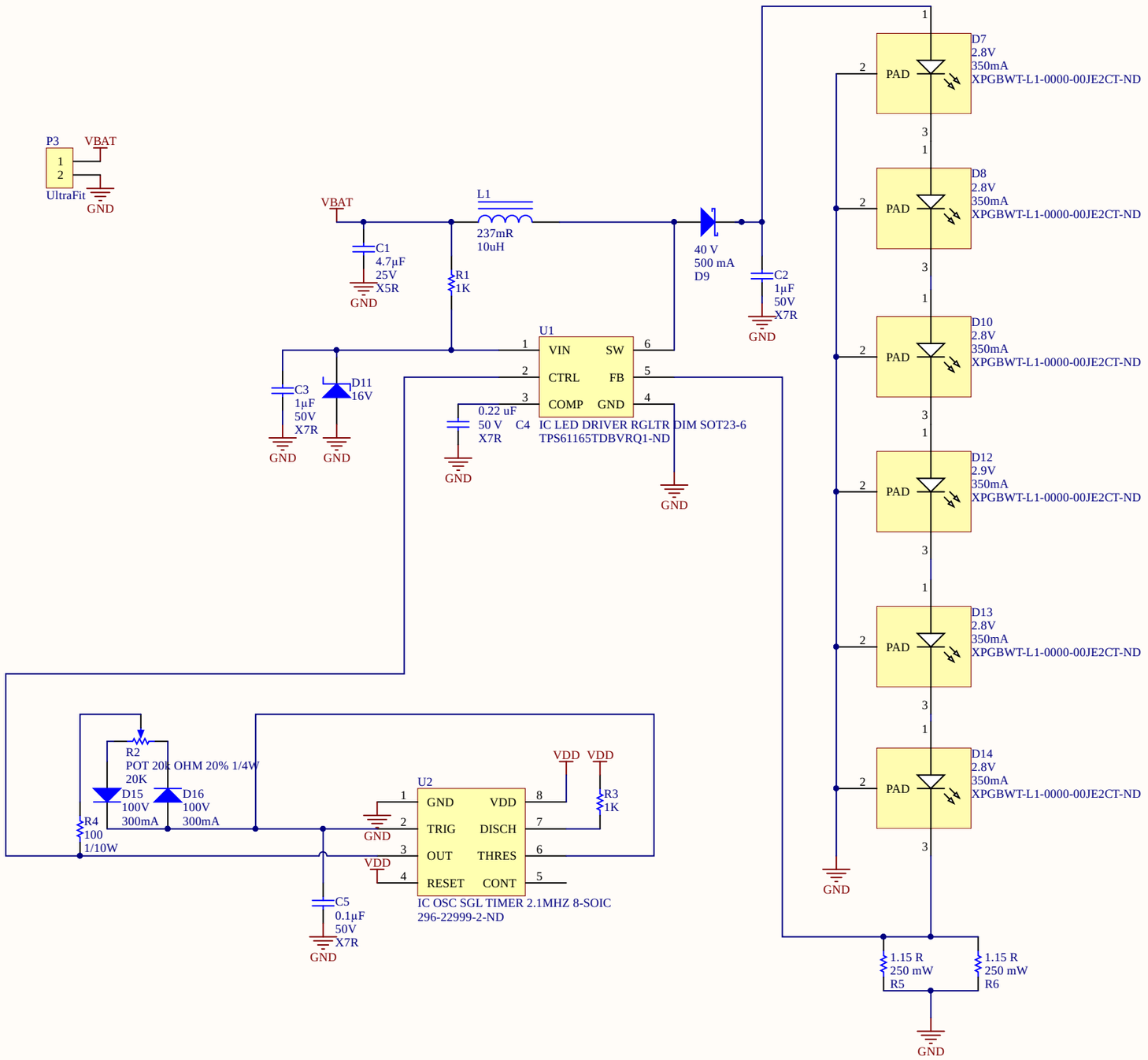


PROJECT	TailLightsPrototype.PrjPCB
DOCUMENT	Title
PART NUMBER	VARIANT [No Variations]
DRAWN BY	REVISION 1.0
LAST MODIFIED 2019-09-14	SHEET * OF *

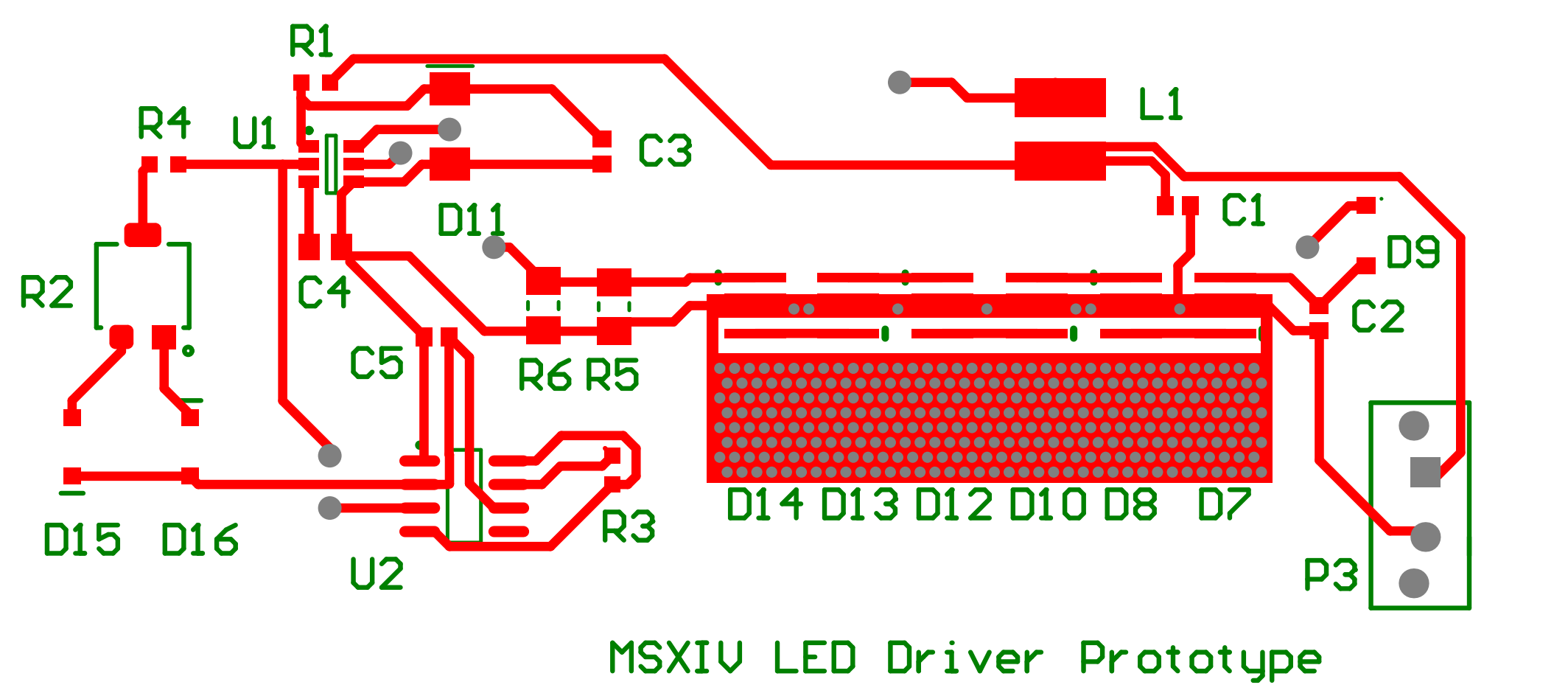
MIDNIGHT SUN

Engineering 5 - 1002
University of Waterloo
(519) 888-4567 x32978
hardware@uwmidsun.com

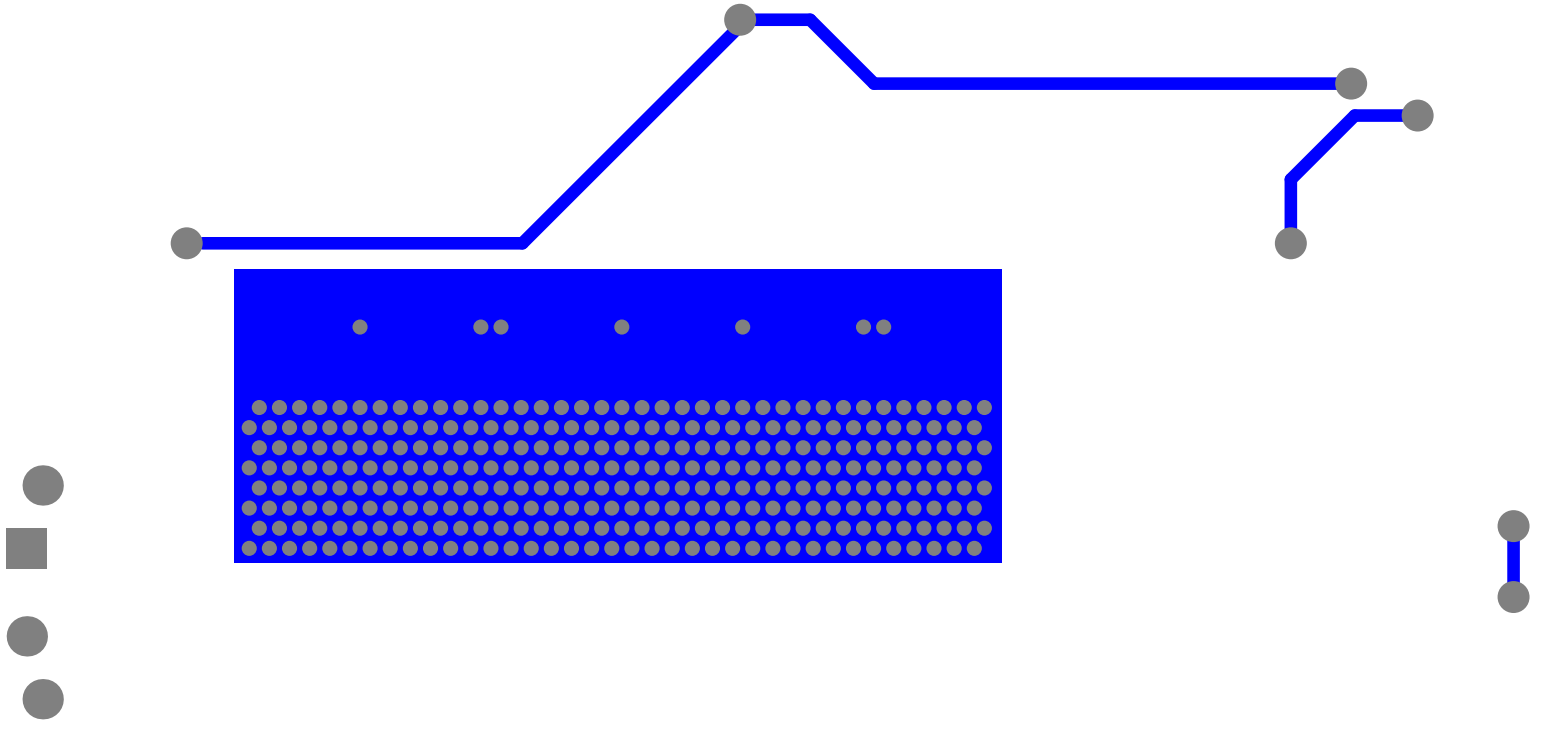
Bill of Materials

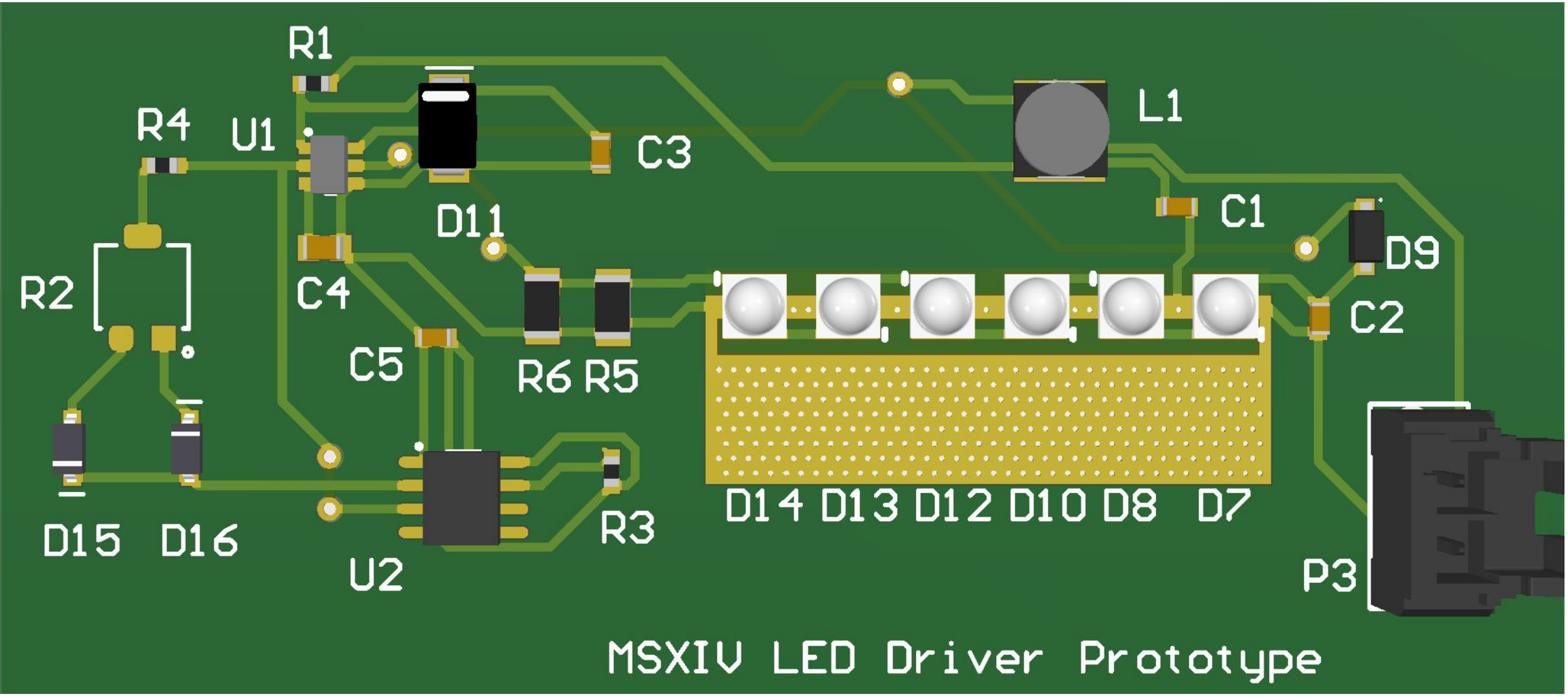
Project:	TailLightsPrototype.PrjPCB
Revision:	1.0
Project Lead:	<Parameter ProjectAuthor not found>
Generated On:	2019-09-14 11:58 AM
Production Quantity:	1
Currency	USD
Total Parts Count:	25

LibRef	Designator	Manufacturer 1	Manufacturer Part Number 1	Supplier 1	Supplier Part Number 1	Supplier Unit Price 1	Quantity	Supplier Subtotal 1
CAP CER 4.7UF 25V 10% X5R 0603	C1	Murata Electronics North America	GRM188R61E475KE11D	Digi-Key	490-7203-1-ND		1	
CAP CER 1UF 50V 10% X7R 0603	C2, C3	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND		2	
CAP CER 0.22UF 50V X7R 0805	C4			Digi-Key	1276-1093-6-ND		1	
CAP CER 0.1UF 50V 10% X7R 0603	C5	AVX Corporation	06035C104KAT2A	Digi-Key	478-5052-1-ND		1	
LED XLAMP COOL WHITE 5700K 2SMD	D7, D8, D10, D12, D13, D14			Digi-Key	SBWT-L1-0000-00JE2CT-ND		6	
DIODE SCHOTTKY 40V 500MA SOD123	D9			Digi-Key	MBR0540DKR-ND		1	
DIODE ZENER 16V 5W DO-214AA (SMB)	D11			Digi-Key	SMBJ5353B-TPMSCT-ND		1	
DIODE GEN PURP 100V 300MA SOD123	D15, D16			Digi-Key	1N4148WQ-7-FDICT-ND		2	
FIXED IND 10UH 1.13A 237 MOHM	L1			Digi-Key	445-3209-2-ND		1	
CONN 2POS ULTRA-FIT 0.138"	P3			Digi-Key	WM11701-ND		1	
RES 1K OHM 5% 1/10W 0603	R1, R3			Digi-Key	311-1.0KGRCT-ND		2	
POT 20k OHM 20% 1/4W	R2			Digi-Key	987-1016-1-ND		1	
RES 100 OHM 1% 1/10W 0603	R4	Yageo	RC0603FR-07100RL	Digi-Key	311-100HRCT-ND		1	
RES SMD 1.15 OHM 1% 1/4W 1206	R5, R6			Digi-Key	311-1.15FRDKR-ND		2	
IC LED DRIVER RGLTR DIM SOT23-6	U1			Digi-Key	TPS61165TDBVRQ1-ND		1	
IC OSC SGL TIMER 2.1MHZ 8-SOIC	U2			Digi-Key	296-22999-2-ND		1	
							Total:	$ -



MSXIV LED Driver Prototype




R1
R4
U1
C3
L1
D11
C1
D9
R2
C4
C2
C5
R6 R5
D14 D13 D12 D10 D8 D7
D15 D16
R3
P3
U2
MSXIV LED Driver Prototype

Design Rules Verification Report

Filename : C:\Users\Liam\Documents\UWaterloo\Midnight Sun\Hardware Repository\ha

Warnings 0
Rule Violations 500

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.254mm) (All),(All)	0
Clearance Constraint (Gap=0.1mm) (IsStitchingVia and InNet('GND')),((IsVia and (Not IsStitchingVia)) Or IsPad)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.5mm) (Max=0.5mm) (Preferred=0.5mm) (All)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	492
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	8
Silk to Silk (Clearance=0.254mm) (All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	500

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.152mm < 0.254mm) Between Pad D11-1(24.23mm,28.6mm) on Top Layer And Via (24.23mm,30.48mm)
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad D12-2(50.8mm,20.98mm) on Top Layer And Via (48.4mm,20.8mm) from
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad D12-2(50.8mm,20.98mm) on Top Layer And Via (53.2mm,20.8mm) from
Minimum Solder Mask Sliver Constraint: (0.007mm < 0.254mm) Between Pad D8-2(60.96mm,20.98mm) on Top Layer And Via (58.8mm,20.8mm) from
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U1-1(16.658mm,29.55mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U1-2(16.658mm,28.6mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U1-4(19.058mm,27.65mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U1-5(19.058mm,28.6mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (39.2mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (39.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (39.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (39.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.8mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (40.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.2mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.6mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (41.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.8mm,16mm) from Top Layer to Bottom Layer And Via

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (42.8mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.2mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (43.6mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.8mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (44.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.2mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.6mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (45.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,13.6mm) from Top Layer to Bottom Layer And Via

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (46.8mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.2mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (47.6mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.8mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (48.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.2mm,16mm) from Top Layer to Bottom Layer And Via

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.2mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.6mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (49.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (50.8mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.2mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (51.6mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,16mm) from Top Layer to Bottom Layer And Via

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.8mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (52.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.2mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.6mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (53.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (54.8mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.2mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.6mm,16mm) from Top Layer to Bottom Layer And Via

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (55.6mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.8mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (56.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.2mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.6mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (57.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.8mm,16mm) from Top Layer to Bottom Layer And Via

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (58.8mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.2mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (59.6mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.8mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (60.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.2mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.6mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (61.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,13.6mm) from Top Layer to Bottom Layer And Via

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (62.8mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.2mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (63.6mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.4mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.8mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.8mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.8mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (64.8mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.2mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.2mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.2mm,16mm) from Top Layer to Bottom Layer And Via

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.2mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.2mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.6mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.6mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.6mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (65.6mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.4mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.8mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.8mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.8mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (66.8mm,17.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.2mm,12mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.2mm,13.6mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.2mm,15.2mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.2mm,16.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.6mm,12.8mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.6mm,14.4mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.6mm,16mm) from Top Layer to Bottom Layer And Via
Minimum Solder Mask Sliver Constraint: (0.091mm < 0.254mm) Between Via (67.6mm,17.6mm) from Top Layer to Bottom Layer And Via

Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Arc (74.47mm,26.74mm) on Top Overlay And Pad D9-1(73.66mm,26.4mm)
Silk To Solder Mask Clearance Constraint: (0.15mm < 0.254mm) Between Pad D10-3(55.88mm,19.48mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.247mm < 0.254mm) Between Pad D11-2(24.23mm,32.664mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.15mm < 0.254mm) Between Pad D12-3(50.8mm,22.48mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.15mm < 0.254mm) Between Pad D13-3(45.72mm,19.48mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.15mm < 0.254mm) Between Pad D14-3(40.718mm,22.48mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.15mm < 0.254mm) Between Pad D7-3(66.04mm,19.48mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.15mm < 0.254mm) Between Pad D8-3(60.96mm,22.48mm) on Top Layer And Track